

PDM: Rev:F

**STATUS**Released

Printed: Jul 31, 2006

NOTES:

(1.) <u>M</u>AT'L

HOUSING: LCP CONTACT: COPPER ALLOY

**PLATING** 

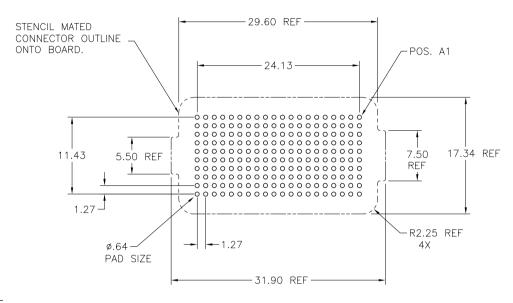
CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Aq/0.5Cu

2. OVERALL BOARD-TO-BOARD STACK HEIGHTS AVAILABLE USING THIS CONNECTOR (84517):

MATED HEIGHT	WITH PLUG P/N						
4mm	84516						
10mm	84530						

- 3. SEE SK-47384 FOR MATING RESTRICTIONS WITH EARLIER DESIGN VERSIONS.
- (4.) PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- (5.) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (6.) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

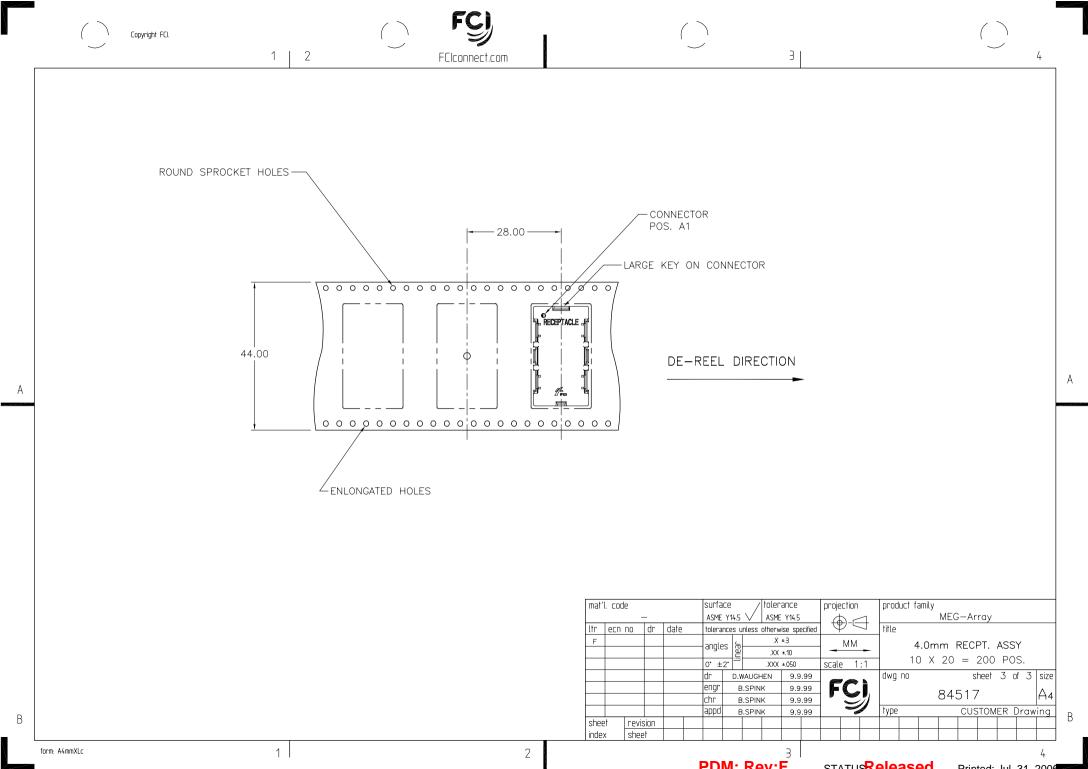
1



BOARD PATTERN

mat′	l. code	surface /			tolerance		projection			product family												
— ASME Y14.5 ✓ ASME Y14.5								4	) _	1	MEG-Array											
ltr	ecn n	o dr	date		tolerances unless otherwise specified					7	ク <	J	title									
F					angles 🖫			.X ±.3			ММ			4.0mm RECPT. ASSY								
					_	-1.≝	1.≝LX		XX ±.10						10 X 20 = 200 POS.							
					0° ±2	-		.XXX	±.050		scale	1	:1	10 × 20 = 200 POS.								
					dr	D.V	VAUGHEN		9.9.	99		C	CJ	dwg	no			S	heet	2 0	f 3	size
					engr	В	.SPIN	K	9.9.99 9.9.99	99				04517							۱, ۱	
					chr	В	B.SPINK			99	B			84517 A						A4		
					appd	pd B.SPIN		PINK 9		99		-		type CUSTOMER Drawing						ing		
shee	et r	evision																				
index	x s	sheet																				

PDM: Rev:F



PDM: Rev:F

STATUS Released

Printed: Jul 31, 2006